



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20200212002
Datasheet for ISO7740-Q1, ISO7741-Q1, ISO7742-Q1
Information Only

Date: March 19, 2020

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE
ISO7741QDWRQ1

CUSTOMER PART NUMBER
39740003-001

Technical details of this Product Change follow on the next page(s).

PCN Number:	20200212002	PCN Date:	Mar. 18, 2020
Title:	Datasheet for ISO7740-Q1, ISO7741-Q1, ISO7742-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



ISO7740-Q1, ISO7741-Q1, ISO7742-Q1

SLLSEU0C – NOVEMBER 2016 – REVISED FEBRUARY 2020

Changes from Revision B (June 2018) to Revision C

Page

• Made editorial and cosmetic changes throughout the document	1
• Changed From: "Isolation Barrier Life: >40 Years" To: ">100-year projected lifetime at 1500 V _{RMS} working voltage" in Features	1
• Added "Up to 5700 V _{RMS} isolation rating" in Features	1
• Added "Up to 12.8 kV surge capability" in Features	1
• Added "±8 kV IEC 61000-4-2 contact discharge protection across isolation barrier" in Features	1
• Changed VDE standard name From: DIN V VDE V 0884-11:2017-01 To: DIN VDE V 0884-11:2017-01 throughout the document	1
• Updated list of applications in Applications section.....	1
• Updated Simplified Schematic to show two isolation capacitors in series per channel instead of a single isolation capacitor	1
• Added extra-wide SOIC (DWW-16) package information for ISO7741-Q1 in the datasheet	4
• Added "Contact discharge per IEC 61000-4-2" specification of ±8000 V in ESD Ratings	7
• Added the following table note to <i>Data rate</i> specification: "100 Mbps is the maximum specified data rate, although higher data rates are possible."	7
• Changed ISO7741-Q1 P _{D1} or Maximum power dissipation by side-1 From: 50 mW To: 75 mW and P _{D2} or Maximum power dissipation by side-2 From: 150 mW To: 125 mW in Power Rating table.....	8
• Changed V _{IORM} value for DW-16 package From: "1414 V _{PK} " To: "2121 V _{PK} " in Insulation Specifications table	9
• Changed V _{IOWM} values for DW-16 package From: "1000 V _{RMS} " and "1414 V _{DC} " To: "1500 V _{RMS} " and "2121 V _{DC} " in Insulation Specifications table	9
• Added 'see Figure 30 ' to TEST CONDITIONS of V _{IOWM} specification in Insulation Specifications	9
• Changed V _{IOSM} TEST CONDITIONS From: "Test method per IEC 60065" To: "Test method per IEC 62368-1" in Insulation Specifications table	9
• Updated certification information in Safety-Related Certifications table	10
• Corrected ground symbol for 'Input (ISO774xF)' schematic in Device I/O Schematics	27
• Updated Figure 24 by changing CAN transceiver From: SN65HVD231Q To: TCAN1042-Q1 and transformer driver From: SN6501-Q1 To: SN6505x-Q1	28
• Added Insulation Lifetime sub-section under Application Curve section.....	30
• Added SN6505x-Q1 reference in Power Supply Recommendations section	31
• Added 'How to use isolation to improve ESD, EFT, and Surge immunity in industrial systems' application report to Documentation Support section	33
• Added SN6505x-Q1 data sheet reference in Documentation Support section	33

The datasheet number will be changing.		
Device Family	Change From:	Change To:
ISO7740-Q1, ISO7741-Q1, ISO7742-Q1	SLLSEU0B	SLLSEU0C
Reason for Change:		
To accurately reflect device characteristics.		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):		
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.		
Changes to product identification resulting from this PCN:		
None.		
Product Affected:		
See page 2		

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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